

Power Supply Design Seminar

Introduction to the trans-inductor voltage regulator (TLVR)

Authors

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Agenda/overview

- Background and motivation
- Transinductor voltage regulator (TLVR) topology introduction
- Practical considerations
- Conclusion

Voltage regulator design challenges

- **Silicon technology continues to shrink** (but this is slowing) 3-nm digital \rightarrow lower
- Application-specific integrated circuit (ASIC) **operating voltages remain** 0.7 V to 1.0 V (up to 1.8 V)
- High-core-count designs and chiplet revolution driving **rapid increase in operating currents** >1,000-A designs
- Extreme load transient requirements 1,000 A/µs, ±3%

Motivation for TLVR: Improving transient response

Motivation for TLVR: Improving transient response

Buck converter vs. TLVR topology

- **Buck-derived** topology optimized for fast transient response
- TLVR is a new twist on the coupledinductor buck converter
- **When it makes sense:**
	- High phase count (>six phases)
	- High di/dt load transient
	- Moderate voltage ripple

Traditional coupled inductor

Traditional coupled inductor (two phase)

 I_{L1} I_1 I_{L2} Φ_1 Φ_2 **Two-phase coupled inductor** Source: Eaton Phase 2 Phase 1

- Multiple windings share a single core
- Typical coupling coefficient: ≈ 0.5 to 0.7
- Higher power density
- Customized design for phase count/layouts

Difficult to extend to higher phases

- **Challenge:** Symmetry is required for equal coupling among phases
- **Challenge:** Complex geometry required to maintain symmetry at higher phase counts

Coupling allows high steady state inductance (low ripple) and low transient inductance (fast transient)

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Indirect-coupled inductor

Indirect-coupled inductor (two phase)

TLVR: Indirect-coupling and compensating inductor (L^c)

- Phases are coupled symmetrically without a sharing core
- **Simple core geometry, scalable solution**
- **Challenging to control coupling**

TLVR topology overview

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TLVR operating principle: Steady state

off

on

 I_{Lc} increases

TLVR steady-state operation (four-phase example, no overlap)

TLVR operating principle: Transient step-up

TLVR operating principle: Transient step-down

Side-by-side comparison: Load step-up

Side-by-side comparison: Load step-down

TEXAS INSTRUMENTS

DC load line further reduces output capacitance

DC load-line (DCLL) behavior is **identical** between buck and TLVR designs

L_c **as an AC inductor –** I_{LC} during a transient

High-frequency transient (65 kHz)

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Jh.

VR vs. TLVR efficiency comparison (L_{BUCK} = L_M = L_C)

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Dynamic phase shedding

Example side -by -side design

More transient margin with 45% reduction in output capacitance required

Practical considerations

Lc inductor selection

- Typically select L_c between L_m and 1.25 \times L_m
- Minimal root-mean-square current (RMS) required

 $I_{\text{rms}(L_c)} \approx$ $\Delta I_{\rm LC}$ 12

• High saturation current required

 $I_{\text{sat}} \gg t_{\text{resp}} \times$ $N_{on (step)} \times V_{IN} - N_{total} \times V_{OUT}$ L_c

• Voltage across L_c can be $\gg V_{\text{IN}}$

 $V_{LC(max)} = N_{on (step)} \times V_{IN} - N_{total} \times V_{OUT}$

Example L^c selection

Output-ripple cancellation

Reduced ripple voltage: Interleaved TLVR

- For high-phase-count (>12 phase) designs, creating two (or more) L_{c} loops achieves interleaving
- May also be advantageous for layout and electromagnetic interference (EMI) concerns (reduced L_{c} frequency, reduced maximum L_{c} voltage)

Typical power-stage layout

• Interleaving phase fire order reduces crosstalk and reduces input capacitor stress

- L_c current still carries high current in a transient
- Recommend ≊50 mils

Printed circuit board layout: Multiside power delivery

Example:

- 32-phase design
- Two L_c interleaved design

Recommendations:

- Symmetrical power train and L_{c} layout
- Decoupling and current-resistance (IR) drop on input traces
- PWM pin trace capacitance
	- Controller PWM drive strength
- Current-sense trace capacitance
	- Low-pass filter effect for current monitor (Imon) signals

TLVR-optimized controllers and power stages

TLVR-optimized power stages

High bandwidth, real current information reporting

Part number Current rating Package/features CSD95440 80-A peak, 40 A_{RMS} 5 mm \times 6 mm (voltage Imon) CSD95510 90-A peak, 50 A_{PMS} $\left| 4 \text{ mm} \times 6 \text{ mm} \text{ (voltage lmon)} \right|$ CSD95560 90-A peak, 50 A_{RMS} 4 mm \times 6 mm (current Imon) CSD95520 60-A peak, 30 A_{RMS} $\left| 4 \text{ mm} \times 5 \text{ mm}$ (voltage Imon) CSD95570 60-A peak, 30 A_{RMS} 4 mm \times 5 mm (current Imon)

TLVR-optimized controllers

Load transient detection based on PWM timing

Conclusion

Summary

- Introduced the TLVR topology
	- Buck-derived topology similar to coupled inductors for high-phase-count designs
	- Better modularity and reuse for TLVR, since inductors do not share a core
	- Significant output capacitor savings given coupled-inductor behavior
- Practical considerations for TLVR designs
	- TLVR designs typically have higher ripple current and voltage vs. buck
	- Interleaving for high-phase-count designs
	- Printed circuit board layout for TLVR designs is similar to buck, with L_{c} loop added
- TLVR-optimized components
	- High-bandwidth and system-level optimizations needed to optimize for TLVR designs

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